

Material Composition Data



Product: GXO-3301

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GXO-3301 - 1.8~3.3V SM Oscillator

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Base	Ceramic	Al ₂ O ₃	1344-28-1	12.190	80.62
	Ceramic	Cr ₂ O ₃ (Non hex)	1308-38-9	0.070	0.46
	Ceramic	Mo	7439-98-7	0.100	0.66
	Ceramic	SiO ₂	14808-60-7	0.460	3.04
	Gold plate	Au	7440-57-5	0.370	2.45
	Mo-W	Mo	7439-98-7	0.030	0.20
	Mo-W	W	7440-33-7	1.110	7.34
	Nickel	Ni	7440-02-0	0.790	5.22
Blank	Quartz	SiO ₂	14808-60-7	0.700	100.00
Electrode	Metal	Ag	7440-22-4	0.008	100.00
IC DIE	Gold wire	Au	7440-57-5	2.630	83.95
	IC DIE	Al	7429-90-5	0.004	0.13
	IC DIE	Si	7440-21-3	0.499	15.93
Lid	Ag-Cu	Ag	7440-22-4	0.130	3.80
	Ag-Cu	Cu	7440-50-8	0.050	1.46
	Kovar	Co	7440-48-4	0.520	15.20
	Kovar	Fe	7439-89-6	1.650	48.25
	Kovar	Ni	7440-02-0	0.890	26.02
	Nickel	Ni	7440-02-0	0.180	5.26
Silver Glue	Silicone resin	Ag	7440-22-4	0.020	83.33
	Silicone resin	Si	7440-21-3	0.004	16.67
Total Mass:				22.405 mg	

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